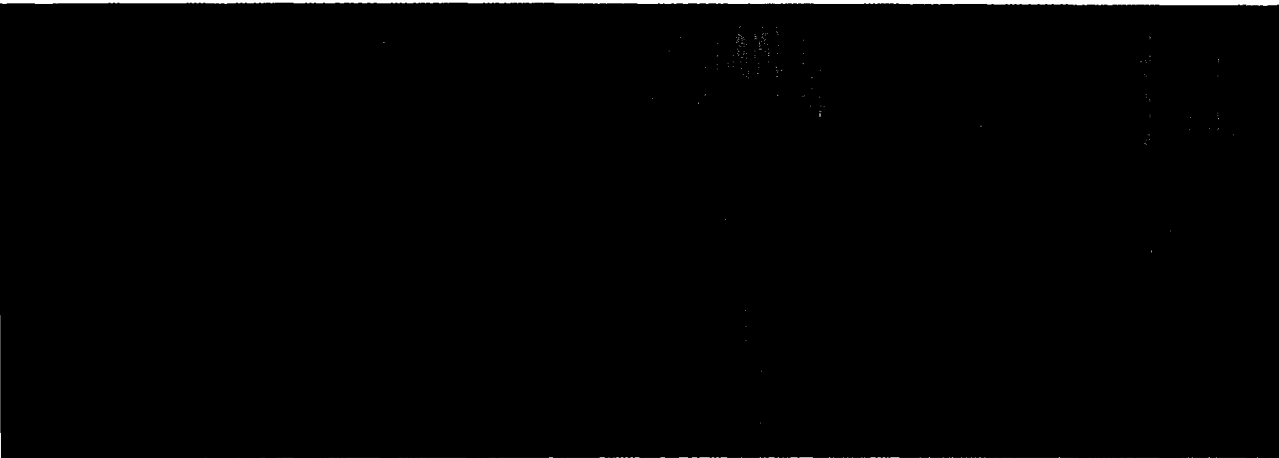


MICROWAVE COMPONENTS

DC to 8.0GHz	Stripline Attenuators (Internally Mounted)	CL 354
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◆ GENERAL FEATURES

The AT-900 series consists of compact, lightweight internally mounted fixed attenuators which can be soldered directly to strip lines, with attenuation from 0 to 10 dB in steps of 1 dB.



◆ OPERATIONAL ENVIRONMENT

Operating temperature; $-10^{\circ}\text{C}\sim+65^{\circ}\text{C}$
Humidity; 0~95%

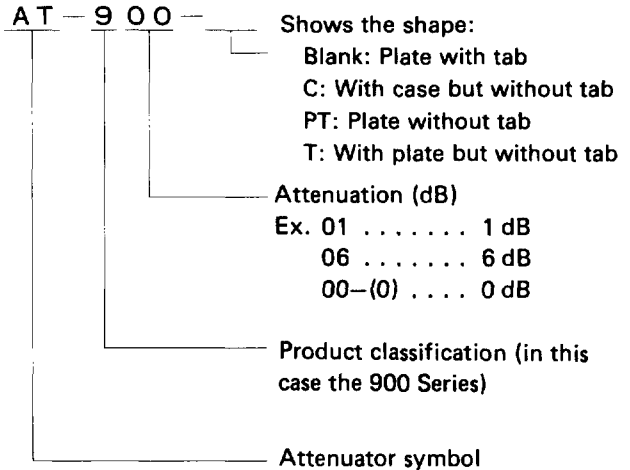
◆ TEST ENVIRONMENT

Vibration resistance; 10~55Hz
Total amplitude; 1.5mm 55~2000Hz 98m/s²
Temperature resistance; $-55^{\circ}\text{C}\sim+85^{\circ}\text{C}$
Impulse resistance; 490m/s²
Testing Method per MIL-STD-202

◆ MATERIAL • FINISH

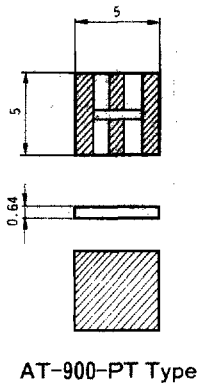
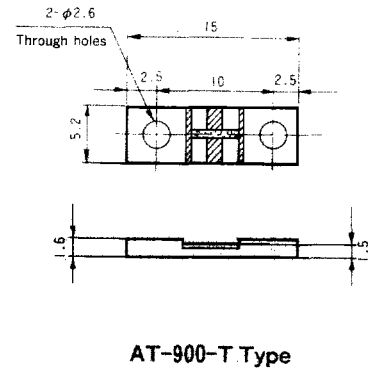
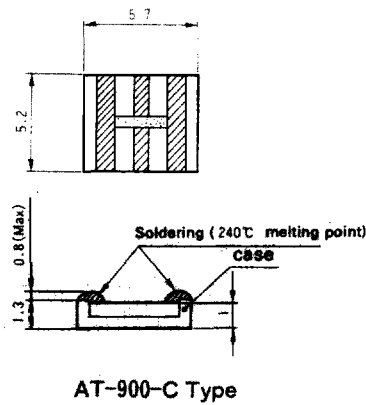
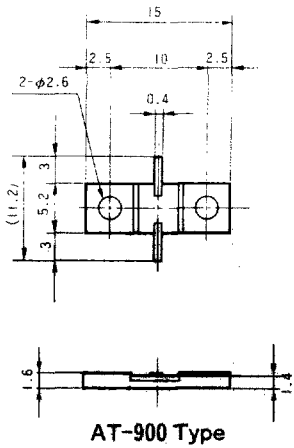
Part Name	Material	Finish
Body	Brass	Nickel-plated
Resistor	Metal film	
Tab	Copper	Nickel-plated

◆ Model No.



MICROWAVE COMPONENTS

◆ DIMENSIONS



◆ SPECIFICATIONS

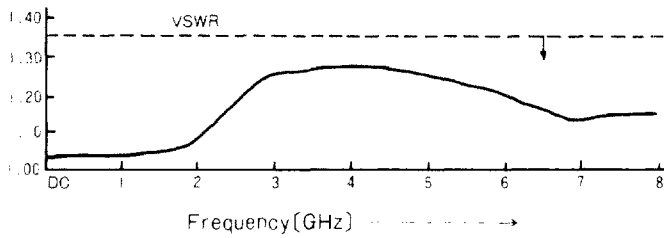
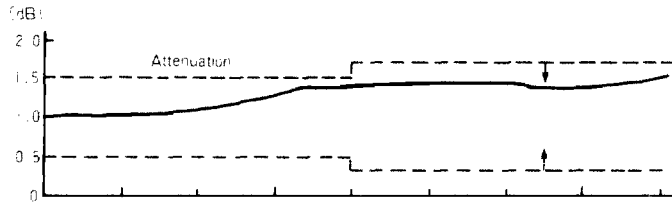
Model No.	Attenuation (dB)		VSWR (Max) DC~ 8GHz	Power (W)	Surface Temperature at Maximum Load (°C Max)	Weight (g)
	DC~4GHz	4~8GHz				
AT-900-(0)	$0^{+0.5}_0$	$0^{+0.7}_0$	1.35	1	+85	1
AT-901	1 ± 0.5	1 ± 0.7	1.35	1	+85	1
AT-902	2 ± 0.5	2 ± 0.7	1.35	1	+85	1
AT-903	3 ± 0.5	3 ± 0.7	1.35	1	+85	1
AT-904	4 ± 0.5	4 ± 0.7	1.35	1	+85	1
AT-905	5 ± 0.5	5 ± 0.7	1.35	1	+85	1
AT-906	6 ± 0.5	6 ± 0.7	1.35	1	+85	1
AT-907	7 ± 0.5	7 ± 0.7	1.35	1	+85	1
AT-908	8 ± 0.5	8 ± 0.7	1.35	1	+85	1
AT-909	9 ± 0.5	9 ± 0.7	1.35	1	+85	1
AT-910	10 ± 0.5	10 ± 0.7	1.35	1	+85	1

MICROWAVE COMPONENTS

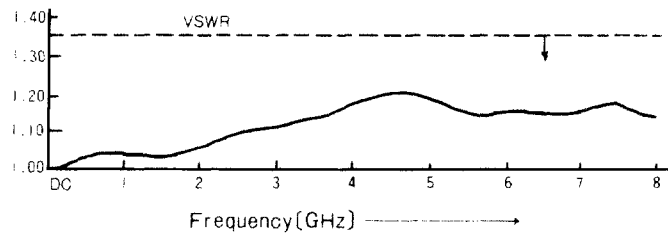
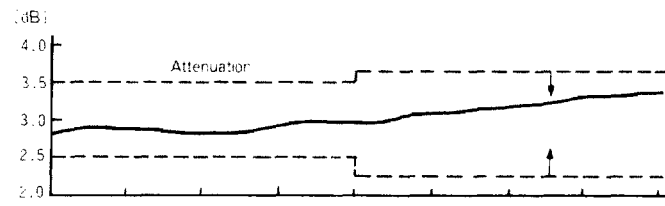
Model No.	Frequency Range (GHz)	Attenuation (dB)	VSWR (Max)	Power (W)	Surface Temperature at Maximum Load (°C Max)	Weight (g)
AT-900-(0)-C	DC~ 4	0 ₀ ^{+0.5}	1.3	1	+85	0.5
AT-900-(0.5)-C	DC~ 4	0.5±0.5	1.3	1	+85	0.5
AT-901-C	DC~ 4	1±0.5	1.3	1	+85	0.5
AT-900-(1.5)-C	DC~ 4	1.5±0.5	1.3	1	+85	0.5
AT-902-C	DC~ 4	2±0.5	1.3	1	+85	0.5
AT-903-C	DC~ 4	3±0.5	1.3	1	+85	0.5
AT-904-C	DC~ 4	4±0.5	1.3	1	+85	0.5
AT-900-(0)-T	DC~ 4	0 ₀ ^{+0.5}	1.3	1	+85	1
AT-901-T	DC~ 4	1±0.5	1.3	1	+85	1
AT-902-T	DC~ 4	2±0.5	1.3	1	+85	1
AT-903-T	DC~ 4	3±0.5	1.3	1	+85	1
AT-904-T	DC~ 4	4±0.5	1.3	1	+85	1
AT-905-T	DC~ 4	5±0.5	1.3	1	+85	1
AT-906-T	DC~ 4	6±0.5	1.3	1	+85	1
AT-907-T	DC~ 4	7±0.5	1.3	1	+85	1
AT-908-T	DC~ 4	8±0.5	1.3	1	+85	1
AT-909-T	DC~ 4	9±0.5	1.3	1	+85	1
AT-910-T	DC~ 4	10±0.5	1.3	1	+85	1
AT-900-(0)-PT	DC~ 4	0 ₀ ^{+0.5}	1.3	1	+85	0.1
AT-901-PT	DC~ 4	1±0.5	1.3	1	+85	0.1
AT-902-PT	DC~ 4	2±0.5	1.3	1	+85	0.1
AT-903-PT	DC~ 4	3±0.5	1.3	1	+85	0.1
AT-904-PT	DC~ 4	4±0.5	1.3	1	+85	0.1
AT-906-PT	DC~ 4	6±0.5	1.3	1	+85	0.1
AT-907-PT	DC~ 4	7±0.5	1.3	1	+85	0.1

◆ (Typical) DATA

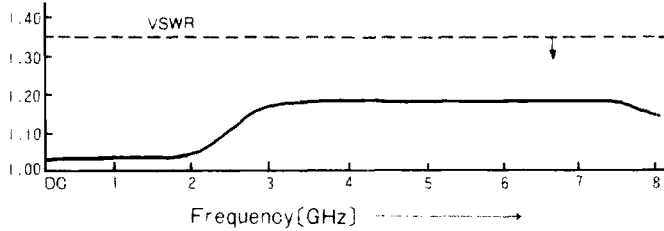
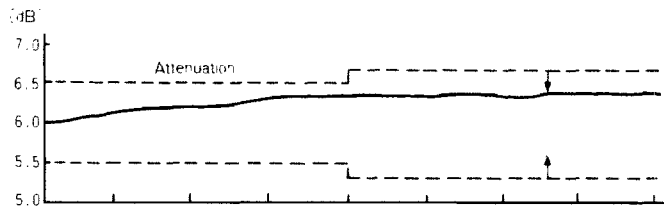
AT-901



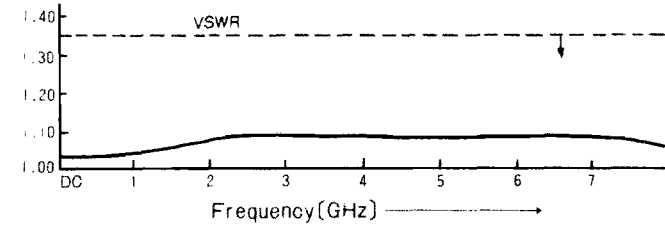
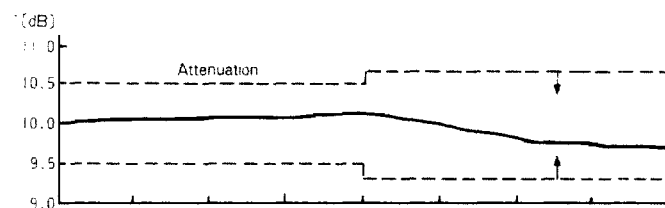
AT-903



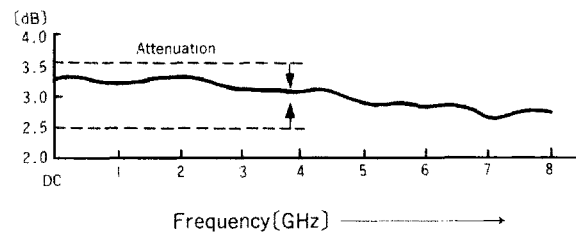
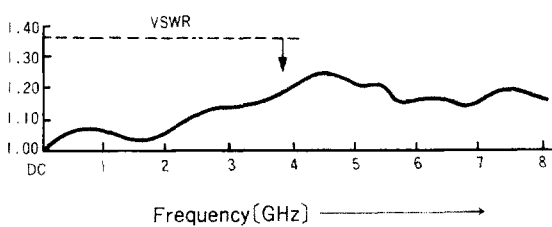
AT-906



AT-910

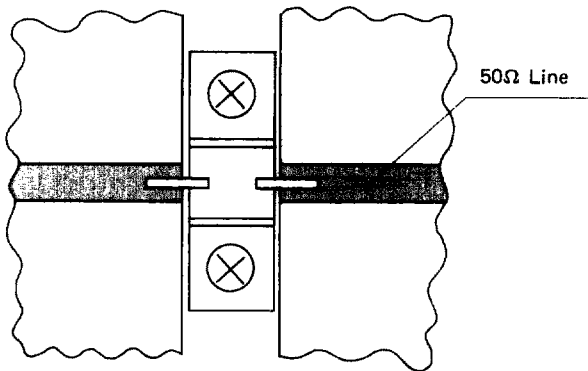


AT-903-T

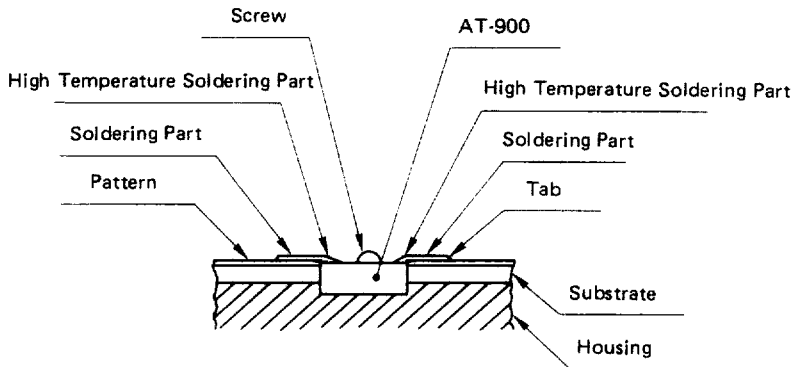


◆ INSTALLATION

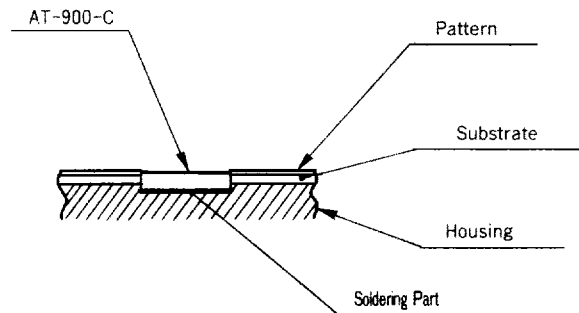
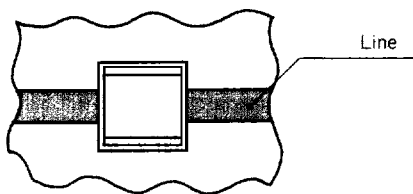
AT-900



- Because the tab of AT-900 series is fixed by high-temperature soldering (280°C melting point), when soldering on the micro strip board, do at a lower temperature.
- Although high frequency characteristic is deteriorated to some extent, slacken the tab to raise its heat reliability upon installing.

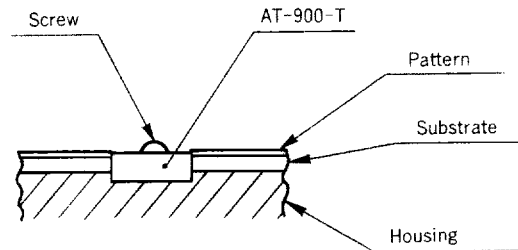
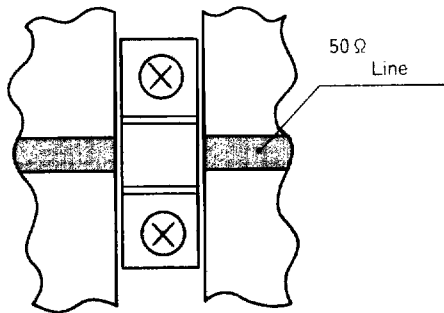


AT-900-C



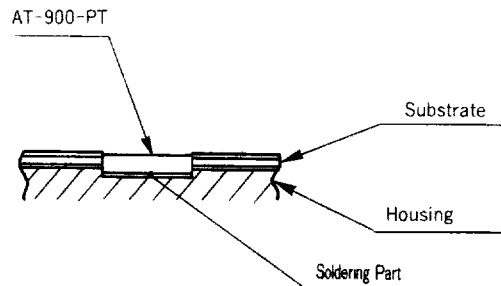
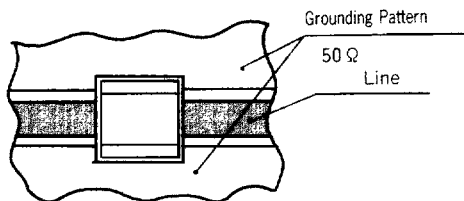
- Take care to keep the temperature below 240°C when soldering the tabs to the housing (ground) because the grounding electrode is soldered to the case with solder having a melting point of 240°C.
- The 50-ohm line is soldered to the AT-900-C center electrode using tabs or bonded using gold wire.
- Solder the tabs quickly to prevent the diffusion of the center electrode (gold electrode).

AT-900-T



- The 50-ohm line is soldered to the AT-900-T center electrode using tabs or bonded using gold wire.
- Solder the tabs quickly to prevent the diffusion of the center (gold) electrode.

AT-900-PT



- In a separate AT-900-PT, the ground on the resistor surface is not connected to the ground on the back. To maintain excellent high-frequency performance, connect the ground on the resistor surface to the housing (ground) by modifying the processing and mounting of the substrate.
- To prevent diffusion of the center (gold) electrode, solder the tabs quickly when the connection is made by soldering the tabs.